

SID

Factory: Rot am See

Article:

ML6

Provided:

Customer:

Date:

03.04.2026

**WÜRTH
ELEKTRONIK**
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	139		2	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		3	
		35	L2		
A-RS-FR4-ML-0.406mm-035+035-TG150-HF-...	50203022	407		4	A01
		35	L3		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	216		5	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		6	
		35	L4		
A-RS-FR4-ML-0.406mm-035+035-TG150-HF-...	50203022	407		7	A02
		35	L5		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	139		8	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		9	
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	10	

B00:

Thickness after Pressing

B00:

1440 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1595 µm

Dmin:

1285 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1550 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1705 µm

Dmin:

1395 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

1518 µm

Version 1.2.20.35

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